

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20230928002.1 Qualification of HFTF as an additional Assembly site for Select Devices Change Notification / Sample Request

Date: September 28, 2023

To:

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team SC Business Services

20230928002.1 Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS54140DGQR	null
TPS54160DGQR	null
TPS54040DGQR	null
TPS54040DGQ	null
TPS54060DGQR	null
TPS54140ADGQR	null
TPS54060ADGQ	null
TPS5401DGQR	null
TPS54160ADGQR	null
TPS54140ADGQ	null
TPS54040ADGQR	null
TPS5401DGQ	null
TPS5401DGQT	null
TPS54040ADGQ	null
TPS54140DGQ	null
TPS54160ADGQ	null
TPS54160DGQ	null

Technical details of this Product Change follow on the next page(s).

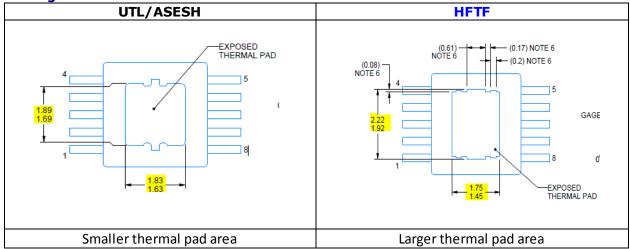
PCN Number: 20230928002.1			002.1	2.1			PCN D	ate:	September 28, 2023			
Title	Title: Qualification of HFTF as an alternate Assembly site for select devices											
Cus	tome	er Conta	ct:	Chan	ige Ma	nagement Team Dept: Q			Qua	uality Services		
Proposed 1 st Ship Date: Dec 2			29, 2	023	Sample req accepted							
*Sa	mple	requests	recei	ived a	fter O	ct 2	9, 2023 will not	be suppo	rted.			
Cha	nge '	Туре:										
Assembly Site				Design			Wafer	Wafer Bump Material				
Assembly Process				Data Sheet			Wafer Bump Process					
★ Assembly Materials				Part number of	art number change			е				
☐ Mechanical Specification				Test Site			Wafer Fab Material					
□ Packing/Shipping/Labeling				Test Process			Wafer Fab Process					
PCN Details												

Description of Change:

Texas Instruments Incorporated is announcing the qualification of HFTF as an additional Assembly site for set of devices listed below. Construction differences are as follows:

	UTL	ASESH	HFTF
Wire type	1.3mil Au, 1.3mil Cu	1.3mil Au, 1.0mil Cu	1.0 mil Cu
Mold Compound	CZ0094	EN2000515	R-32
Mount Compound	PZ0013	EY1000063	A-24

Package Outline Differences:



Reason for Change:

Supply continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	RoHS REACH		IEC 62474		
☑ No Change	☑ No Change	☑ No Change	☑ No Change		

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City		
UTL	NS2	THA	Bangpakong		
ASESH	ASH	CHN	Shanghai		
HFTF	HFT	CHN	Hefei		

Sample product shipping label (not actual product label)



MADE IN: Malaysia MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04

OPT: T0:1750



(1P) SN74LS07NSR (D) 0336)LOT: 3959047ML 4W) TKY(1T) 7523483SI2

(2P) REV: (V) 0033317 (21L) CCO:USA (20L) CSO: SHE (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

TPS5401DGQ	TPS54040DGQ	TPS54060DGQR	TPS54160ADGQ
TPS5401DGQR	TPS54040DGQR	TPS54140ADGQ	TPS54160ADGQR
TPS5401DGQT	TPS54060ADGQ	TPS54140ADGQR	TPS54160DGQ
TPS54040ADGQ	TPS54060ADGQR	TPS54140DGQ	TPS54160DGQR
TPS54040ADGQR	TPS54060DGQ	TPS54140DGQR	

Qualification Report

Approve Date 01-AUGUST -2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: TPS54160ADGQR	QBS Reference: LM5165XQDGSRQ1	QBS Reference: TPS40210QDGQRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	QBS	3/231/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	QBS	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	QBS	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	QBS	3/135/0	-
SD	С3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	QBS	1/15/0	-

QBS: Qual By Similarity

Qual Device TPS54160ADGQR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at Tl's external Web site: http://www.ti.com/

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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